

2.5V to 16V Protection Switch with Blocking FET Control

General Description

The eFuse SY20817A is a highly integrated circuit protection and power management solution in a compact package. The device uses few external components and provides multiple protection modes. It is a robust defense against overload, short circuit, and excessive inrush current conditions.

Extremely low power path resistance R_{DS(ON)} helps to reduce power loss during normal operation. An open drain indicator pin is provided to show the operation status of the device. The device integrates overtemperature protection and autorecovery with hysteresis to protect against overcurrent events.

The current limit level can be easily configured using a single external resistor. For applications with specific voltage ramp requirements, the SST pin can be set with a single capacitor to ensure the desired output ramp rate. Additionally, to prevent current flow from the load to the source during shutdown, an external NFET can be connected in back-to-back (B2B) configuration with the SY20817A output and controlled by the BFET pin.

The SY20817A is available in a compact QFN 2mm×2mm-12pin package.

Features

- Input Voltage Range: 2.5V to 16V
- Extremely Low Power Path Resistance RDS(ON)
- $R_{DS(ON)}=30m\Omega$ (Typical)
- 1A to 5A Programmable Current Limit
- Open Drain Indicator Pin for Operation Status
- ±10% ILIMIT Accuracy at 3A
- Programmable OUT Slew Rate
- Auto output discharge during shutdown
- Built-in Thermal Shutdown
- Compact Package: QFN2x2-12

Applications

- Power Banks
- LCD Panels
- · HDD and SSD Drives
- Set Top Boxes
- Servers / AUX Supplies
- Fan Controls
- PCI/PCIe Cards
- Adapter Powered Devices

Typical Application Circuit

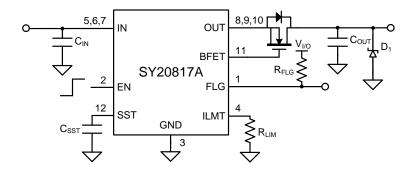
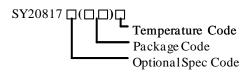


Figure 1. Schematic Diagram



Ordering Information

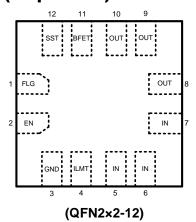


Ordering Number	Package Type	Top Mark
SY20817ATLC	QFN2×2-12	Ye <i>xyz</i>

Device code: Ye

x=year code, y=week code, z= lot number code

Pinout (Top View)



Pin Name	Pin Number	Pin Description
FLG	1	Open drain indicator pin. The pin will be pulled down when overcurrent, short circuit or thermal shutdown occurs. High impedance otherwise.
GND	3	Ground pin.
IN	5,6,7	Input voltage and supply voltage; connect a 0.1 µF or greater ceramic capacitor from IN to GND as close to the device as possible.
OUT	8,9,10	Power-switch output.
BFET	11	Connect this pin to the gate of an external blocking NFET. This pin can be left floating if it is not used.
EN	2	Pull high to enable. Do not leave it floating.
SST	12	Connect a capacitor from this pin to GND to control the ramp rate of the voltage at OUT pin during device turn-on.
ILMT	4	A resistor from this pin to GND will set the overcurrent limit.

Block Diagram

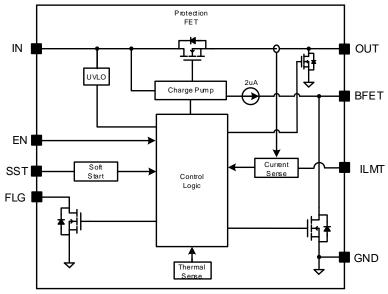


Figure 2. Block Diagram





Absolute Maximum Ratings (Note 1)	
IN. EN. FLG	
OUT	
BFET	
ILMT, SST	
FLG Continuous Output Sink Current	25mA
BFET Continuous Output Sink Current	20mA
Power Dissipation, P_D @ T_A = 25°C	2.7W
Package Thermal Resistance (Note 2)	
heta JA	46°C/W
heta JC	18°C/W
Junction Temperature Range	
Lead Temperature (Soldering, 10 sec.)	260°C
Storage Temperature Range	
Recommended Operating Conditions (Note 3)	
INBFET	2.5V to 16V
BFET	0V to IN+6V
EN	
SST, ILMT	
OUT Continuous Output Current	
FLG Continuous Output Sink Current	0mA to 10mA
Junction Temperature Range	
Ambient Temperature Range	





Electrical Characteristics

 $(-40 \le T_J \le 125^{\circ}\text{C}, V_{IN} = 12 \text{ V}, V_{EN} = 2 \text{ V}, R_{ILMT} = 1.1 \text{k}\Omega, C_{SST} = \text{OPEN}, R_{FLG} = 10 \text{k}\Omega.$ Typical values are at 25°C. All voltages are with respect to GND, unless otherwise specified.)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Input Voltage Range	V _{IN}		2.5		16	V
IN Rising UVLO Threshold	Vuvlo				2.45	V
Voltage					2.40	·
Hysteresis	Vuvlo-HYS			100		mV
Shutdown Current	Ishdn	EN=0V		2		μA
Bias Current	IQ	EN=2V		62		μA
ON Resistance	R _{DS(ON)}	T _J = 25°C	24	30	36	mΩ
GTT TEOLOGISTATION	1 103(011)	T _J = 125°C		45	52	mΩ
		$R_{ILMT} = 5.5k\Omega$	0.80	1.00	1.20	Α
		$R_{\text{ILMT}} = 3.65 \text{k}\Omega$	1.30	1.50	1.70	Α
OUT Overload Current limit	loc	$R_{ILMT} = 2.75 k\Omega$	1.80	2.00	2.20	Α
		$R_{ILMT} = 1.85 k\Omega$	2.70	3.00	3.30	Α
		$R_{ILMT} = 1.1k\Omega$	4.50	5.00	5.50	Α
Soft-Start Time Range	tsst	Note 4	0.5		60	ms
Soft-Start Time Accuracy			-30%		30%	t _{SST}
Turn-On Delay Time	t _{d(ON)}	EN → H to I _{VIN} = 100 mA, 1A resistive load at OUT		200		μs
Turn-Off Delay Time	t _{d(OFF)}	EN → L to 0.9×OUT		100		μs
Output Discharge Resistor	R _{DIS}	V _{IN} =5V, EN=0, V _{OUT} =0.1V		100		Ω
BFET Charging Current	I _{BFET}	V _{BFET} = V _{OUT}		2		μΑ
BFET Clamp Voltage	V _{BFET-MAX}	V _{BFET} - V _{IN}		6.0		V
BFET Discharging Resistance to GND	R _{BFET-DIS}	V _{EN} = 0 V, I _{BFET} = 10mA	15	26	36	Ω
DEET Turn On Duration		EN→H to V _{BFET} = 12V, C _{BFET} = 1nF		6.0		ms
BFET Turn-On Duration	tbfet-on	EN \rightarrow H to V _{BFET} = 12V, C _{BFET} = 10nF		60		ms
DEET Turn Off Duration		EN \rightarrow L to V _{BFET} = 1V, C _{BFET} = 1nF		7.5		μs
BFET Turn-Off Duration	tbfet-off	EN→L to V _{BFET} = 1V, C _{BFET} = 10nF		8.5		μs
EN Pin Logic-High Voltage	V _{ENH}		1			V
EN Pin Logic-Low Voltage	V _{ENL}				0.4	V
FLG Output Low Voltage	V _{FLGL}	I _{FLG} = 1mA			200	mV
Over Current FLG Deglitch	t _{FLG}			2.6		ms
Thermal Shutdown Threshold	T _{SD}			150		°C
Thermal Shutdown Hysteresis	T _{HYS}			20		°C

Note 1: Stresses beyond the "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 2: θ_{JA} is measured in the natural convection at T_A = 25°C on a Silergy's test board.





Note 3: The device is not guaranteed to function outside its operating conditions.

Note 4. Recommended Current Soft-start Time Programming Table:

SST cap (nF)	None	10	47	100
SR (V/ms)	6.67	1.74	0.37	0.17

Recommended formulas for Css and soft-start slew rate calculations:

$$SR_{_{OUT}} = \frac{17\mu}{C_{_{SST}}(nF)}(V/ms)$$

$$t_{_{SST}} = 0.8 \times \frac{VIN}{SR_{_{OUT}}} (ms)$$

(For a 12V application, using a 100nF SST capacitor will result in an OUT rise time of 56ms.)

Note 5. Recommended Current Limit Program Table:

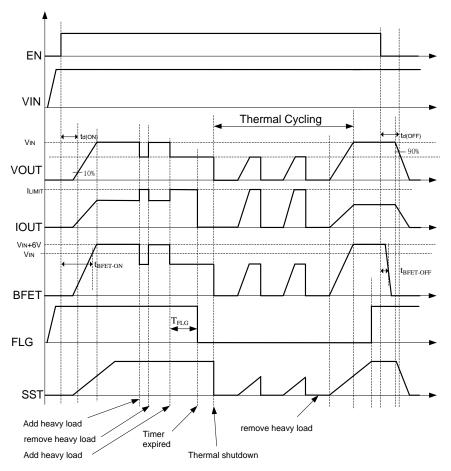
Current Limit Resistance (kΩ)	5.5	2.75	2.2	1.85	1.55	1.4	1.2	1.1
Current Limit (A)	1.0	2.0	2.5	3.0	3.5	4.0	4.5	5.0

Recommended formula for R_{LIM} & current limit calculation:

$$R_{_{ILMT}} = \frac{5.5K}{I_{_{LIM}}}(\Omega)$$

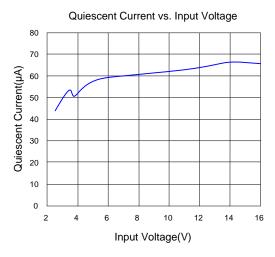


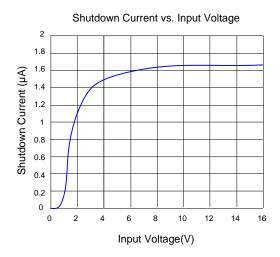
Timing Diagram

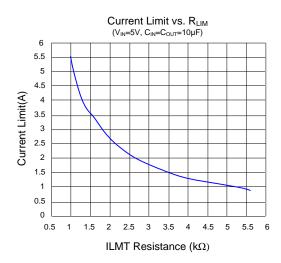


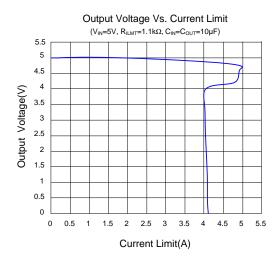


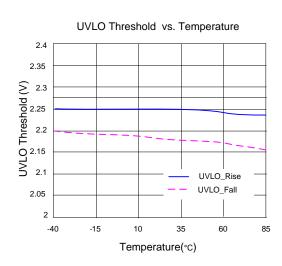
Typical Performance Characteristics

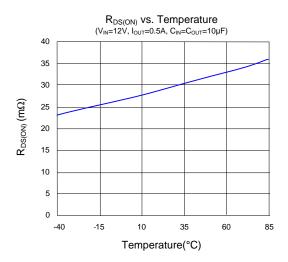






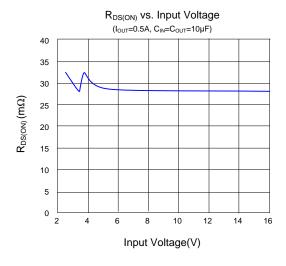


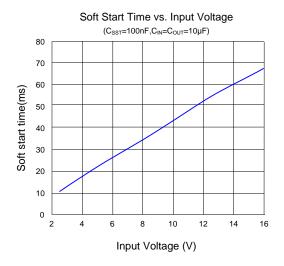


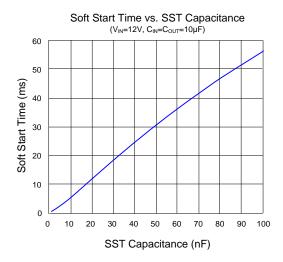


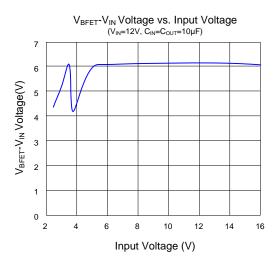


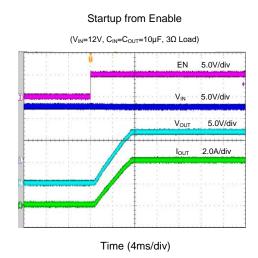


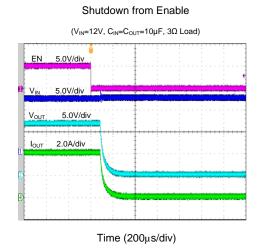










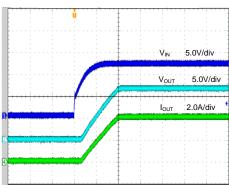






Startup from V_{IN}

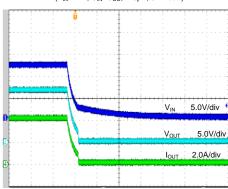
(V_{IN} =12V, C_{IN} = C_{OUT} =10 μ F, 3 Ω Load)



Time (4ms/div)

Shutdown from V_{IN}

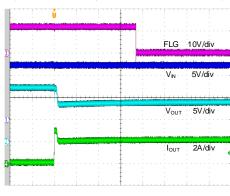
(V_{IN} =12V, C_{IN} = C_{OUT} =10 μ F, 3 Ω Load)



Time (4ms/div)

OCP Response

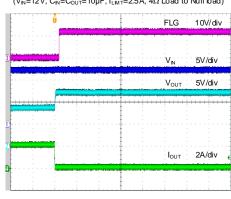
(V $_{\text{IN}}$ =12 V, C_{IN} = C_{OUT} =10 μF , I_{LIMT} =2.5 A, Null load to 4Ω Load)



Time (800µs/div)

OCP Recovery

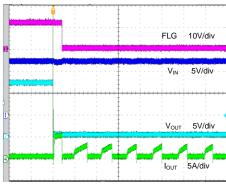
(V_{IN}=12V, C_{IN}=C_{OUT}=10 μ F, I_{LIMT}=2.5A, 4 Ω Load to NuII load)



Time (800µs/div)

Short Circuit Response

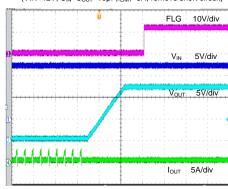
(VIN=12V, C_{IN} = C_{OUT} =10 μ F, I_{LIMT} =5A,NuII load to short circuit)



Time (1ms/div)

Short Circuit Recovery

(VIN=12V, C_{IN} = C_{OUT} =10 μ F, I_{LIMT} =5A, remove short circuit)



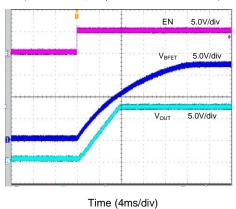
Time (4ms/div)





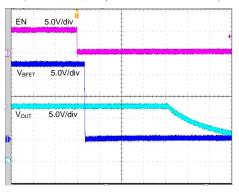
BFET Turn On

(V_{IN} =12V, C_{IN} = C_{OUT} =10 μ F, I_{LIMT} =5A, C_{BFET} =1nF, EN On)



BFET Turn Off

$(V_{IN}\!\!=\!\!12V,\,C_{IN}\!\!=\!\!C_{OUT}\!\!=\!\!10\mu F,\,I_{LIMT}\!\!=\!\!5A,\,C_{BFET}\!\!=\!\!1nF,\,EN\,Off)$



Time (20µs/div)



Application Information

Soft Start Time Programming:

Connect a capacitor from this pin to GND to control the slew rate of the output voltage at power-on. This pin can be left floating to obtain a predetermined slew rate (minimum tsst) on the output.

SST cap (nF)	None	10	47	100
SR (V/ms)	6.67	1.74	0.37	0.17
t _{SST} /V _{IN} =12V(ms)	1.4	5.5	26	56

The C_{SST} and soft-start slew rate can be calculated using the following equations:

$$SR_{OUT} = \frac{17\mu}{C_{SST}(nF)}(V/ms)$$

$$t_{SST} = 0.8 \times \frac{V_{IN}}{SR_{OUT}} (ms)$$

BFET Control:

The SY20817A features a BFET pin designed to disconnect the input supply from the rest of the system in the event of a power failure at VIN. The BFET pin operation is controlled by either an input UVLO event or EN (see Table 1).

When EN is held low or the input voltage is below the UVLO threshold, the internal MOSFET is turned off, and the BFET pin is discharged, effectively blocking current flow from VOUT to VIN. The BFET is capable of sourcing a charging current of 2 μA (typical) and sinking (discharging) current from the gate of the external FET via a 26Ω internal discharge resistor, ensuring a fast turn-off. The BFET clamp voltage is 6V (typical), so it is recommended to choose a low gate voltage N-FET with low $R_{\text{DS(ON)}}$. If the application does not require the reverse current blocking function, the BFET pin can be left floating.

Table 1. BFET

	I abic I. bi L	
EN > V _{EN} H	V _{IN} >V _{UVLO}	BFET MODE
Н	Н	Charge
X	Ĺ	Discharge
L	X	Discharge

Overcurrent Protection:

The device continuously monitors the load current, ensuring it remains within the programmed limit set by $R_{\rm ILMT}.$ Following the startup sequence and during regular operation, the current limit is configured to the IOC (overcurrent limit). For optimal stability of the internal regulation loop, it is recommended to use a 1% resistor within the range of 1.1k to 5.5k for $R_{\rm ILMT}.$

The R_{ILIM} and current limit can be calculated using the following formula:

$$I_{OC} = \frac{5.5K}{R_{ILMT}}(A)$$

When an overcurrent condition (Ioc<I_{LOAD}<1.6×I_{OC}) occurs, the device maintains a constant output current and reduces the output voltage accordingly. Thermal shutdown protection occurs if the fault is present long enough to activate thermal shutdown. The device will remain off until the junction temperature drops by approximately 20°C, then it will restart. The device will continue to cycle on/off until the overcurrent condition is removed.

When a short condition (ILOAD>1.6×IOC) is detected, the power path will be turned off immediately. It will then try to restart again with the current limit.

FLG Response:

The FLG open-drain output is activated (active low) when overtemperature, current limit, or short circuit conditions are detected. During normal operation, the pin is pulled high by an external pull-up resistor. The FLG output stays active until the fault condition is resolved.

The SY20817A is designed to prevent false FLG reporting by incorporating internal deglitch circuits specifically designed for current limit conditions, eliminating the need for additional external circuitry. This ensures that FLG is not accidentally activated during routine operations, such as starting into a heavy capacitive load. Note that overtemperature conditions are not deglitched, causing an immediate activation of the FLG signal.

Supply Filter Capacitor:

A 1 μ F or larger input ceramic capacitor is strongly recommended to be placed close to the device. Without an input capacitor, an output short can cause ringing on the input, which could destroy the internal circuitry when the input transient exceeds the absolute maximum supply voltage, even for a short duration.

Output Filter Capacitor:

A 1µF output ceramic capacitor is recommended to be placed close to the device and output connector to reduce voltage drop during load transient. Higher output capacitor values can further reduce the drop during high-current applications.

In a short circuit scenario, the output could be exposed to a negative voltage caused by the parasitic wiring inductance. It is strongly recommended to connect a





Schottky diode in parallel. This diode will absorb large negative voltage spikes to keep the output voltage within the range of the absolute voltage rating.

Output discharge

The SY20817A integrates an 100Ω pull-down resistor for quick output discharge. The resistor is activated when the switch is turned off.

PCB Layout Guide:

For best performance of the SY20817A, the following

guidelines must be followed:

- Keep all VBUS traces as short and wide as possible and use at least 2-ounce copper for all VBUS traces.
- Place the output capacitor as close to the connector as possible to lower the impedance and inductance between the port and the capacitor and improve transient performance.
- Place the input and output capacitors close to the device and connect them to the ground plane to reduce noise coupling.

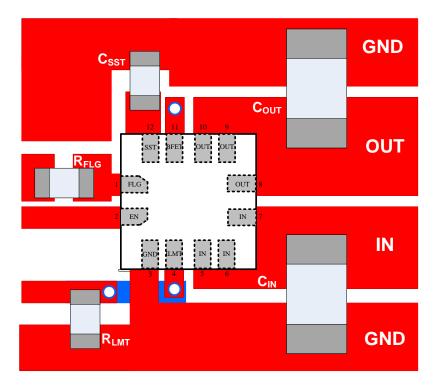


Figure 3. PCB Layout Suggestion



Schematic

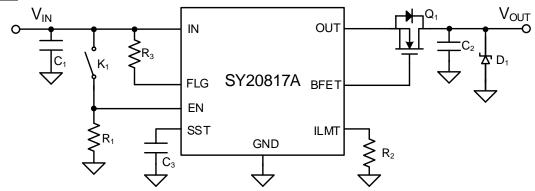


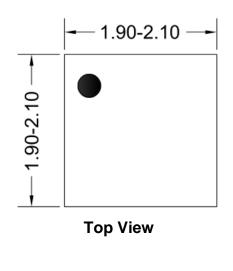
Figure 1. Schematic Diagram

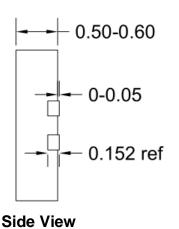
BOM List

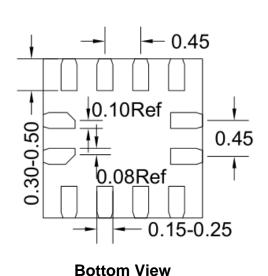
Reference Designator	Description	Part Number	Manufacturer
C ₁ ,C ₂	10μF/25V, 1206, X5R	C3216X5R1E106KT000N	TDK
C ₃	10nF/50V, 0603, X5R	C1608X5R1H103KT000N	TDK
R ₁	1MΩ, 0603	RC0603FR-071ML	YAGEO
R ₂	1.1kΩ, 0603	RC0603FR-071K1L	YAGEO
R ₃	100kΩ, 0603	RC0603FR-07100KL	YAGEO
D ₁	40V, 3A Schottky Diode	SS34	
Q ₁	Null, Short D-S		

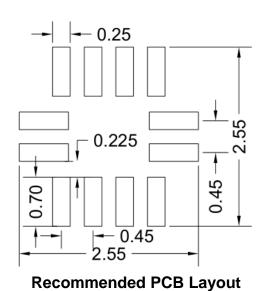


QFN2×2-12 Package Outline Drawing







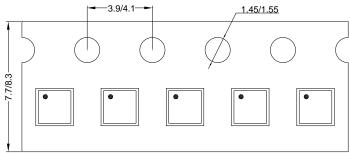


Note: All dimensions are in millimeters and exclude mold flash and metal burr.



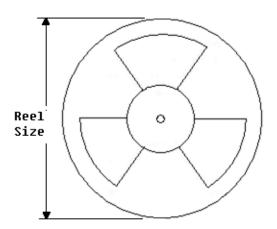
Taping & Reel Specification

QFN2×2 Taping Orientation



Feeding direction ----

Carrier Tape & Reel Specification for Packages



Package type	Tape width (mm)	Pocket pitch (mm)	Reel size (Inch)	Trailer length (mm)	Leader length (mm)	Qty per reel
QFN2×2	8	4	7"	400	160	3000





Revision History

The revision history provided is for informational purposes only and is believed to be accurate, however, not warrantied. Please make sure that you have the latest revision.

Date	Revision	Change
Dec.12, 2023	Revision 1.0	Language improvements for clarity.
Apr.29, 2022	Revision 0.9A	Update the waveforms of OCP Response (Page 9)
Jun. 08, 2018	Revision 0.9	Initial Release





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